

ELECTRONIC PACKAGE WITH STACKED
CONNECTIONS AND METHOD FOR MAKING SAME

ABSTRACT

5 An electronic package which includes first and second circuitized substrates secured together by a solder member which includes a first contact portion for attachment to a printed circuit board and a second contact portion used to bond the two substrates together (e.g., to form a multi-chip module). Semiconductor chips can be positioned on and electrically coupled to the formed solder members.

00764467-011701